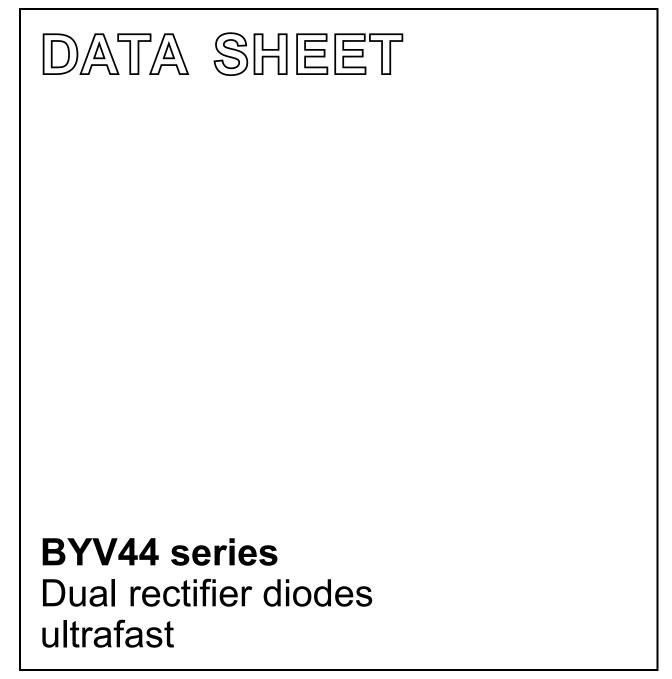
DISCRETE SEMICONDUCTORS



Product specification

October 1998



## Dual rectifier diodes ultrafast

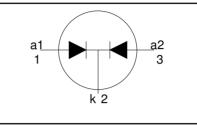
## Product specification

**BYV44** series

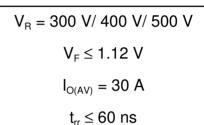
### FEATURES

- · Low forward volt drop
- Fast switching
- Soft recovery characteristic
- High thermal cycling performance
- Low thermal resistance

### SYMBOL



### QUICK REFERENCE DATA



### **GENERAL DESCRIPTION**

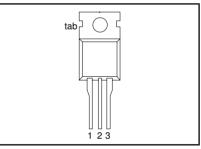
Dual, common cathode, ultra-fast, epitaxial rectifier diodes intended for use as output rectifiers in high frequency switched mode power supplies.

The BYV44 series is supplied in the conventional leaded SOT78 (TO220AB) package.

## PINNING

PIN	DESCRIPTION		
1	anode 1		
2	cathode		
3	anode 2		
tab	cathode		

### SOT78 (TO220AB)



### LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.			UNIT
V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	Peak repetitive reverse voltage Crest working reverse voltage Continuous reverse voltage	<b>BYV44</b> $T_{mb} \le 136^{\circ}C$	- -	<b>-300</b> 300 300 300	<b>-400</b> 400 400 400	<b>-500</b> 500 500 500	V V V
I <sub>O(AV)</sub> I <sub>FRM</sub>	Average rectified output current (both diodes conducting) <sup>1</sup> Repetitive peak forward current per diode	T <sup>··</sup> <sub>mb</sub> ≤ 94 °C	-		30 30		A A
I <sub>FSM</sub>	Non-repetitive peak forward current per diode.	t = 10  ms t = 8.3  ms sinusoidal; with reapplied $V_{\text{RRM(max)}}$	-		150 160		A A
T <sub>stg</sub> T <sub>i</sub>	Storage temperature Operating junction temperature	* HHM(max)	-40 -		150 150		Ĵ. Ĵ

### THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R <sub>th j-hs</sub> R <sub>th j-a</sub>	heatsink	per diode both diodes conducting in free air.		- - 60	2.4 1.4 -	K/W K/W K/W

**<sup>1</sup>** Neglecting switching and reverse current losses.

For output currents in excess of 20 A, the cathode connection should be made to the metal mounting tab.

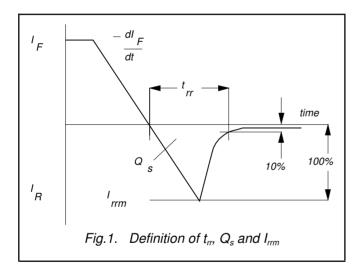
## Dual rectifier diodes ultrafast

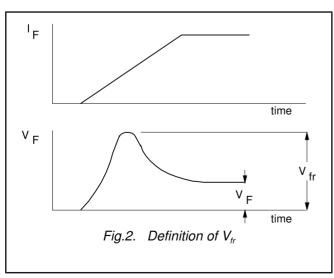
### BYV44 series

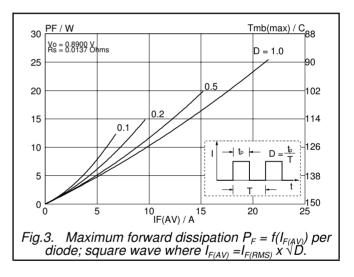
### **ELECTRICAL CHARACTERISTICS**

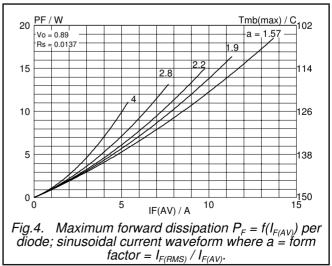
characteristics are per diode at  $T_i = 25$  °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	Forward voltage	I <sub>F</sub> = 15 A; T <sub>i</sub> = 150°C	-	0.95	1.12	V
	-	$I_{\rm F} = 15 {\rm A}^{-1}$	-	1.08	1.25	V
		$I_{\rm F} = 30  {\rm A}$	-	1.15	1.36	V
I <sub>B</sub>	Reverse current	$\dot{V}_{R} = V_{RRM}$	-	10	50	μA
		$V_{R}^{T} = V_{RRM}^{T}; T_{j} = 100 \degree C$ $I_{F} = 2 \ A \ to \ V_{R} \ge 30 \ V;$	-	0.3	0.8	mΑ
Q <sub>s</sub>	Reverse recovery charge	$I_F = 2 \text{ A to } V_B \ge 30 \text{ V};$	-	40	60	nC
-		$dI_{\rm F}/dt = 20  {\rm A}/{\rm \mu s}$				
t <sub>rr</sub>	Reverse recovery time	$I_F = 1 \text{ A to } V_R \ge 30 \text{ V};$	-	50	60	ns
	-	$dI_F/dt = 100 \text{ Å}/\mu \text{s}$				
I <sub>rrm</sub>	Peak reverse recovery current	$I_{\rm F} = 10 \text{ A to } V_{\rm B} \ge 30 \text{ V};$	-	4.2	5.2	Α
	,	$dI_{\rm F}/dt = 50 \text{ A}/\mu \text{s}; T_{\rm i} = 100^{\circ}\text{C}$				
V <sub>fr</sub>	Forward recovery voltage	$I_{F} = 10 \text{ A}; dI_{F}/dt = 10 \text{ A}/\mu \text{s}$	-	2.5	-	V



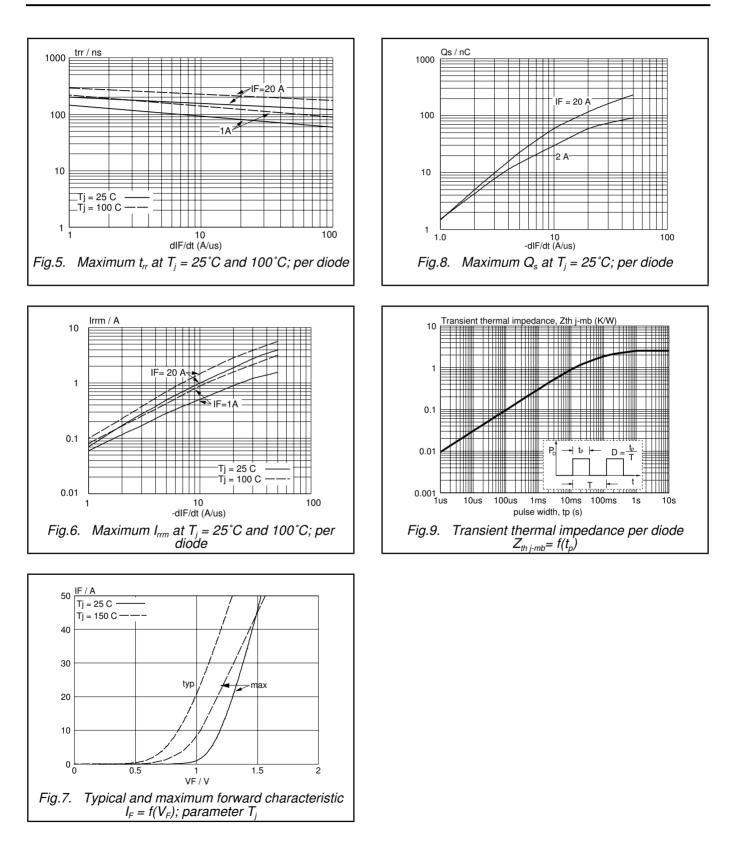






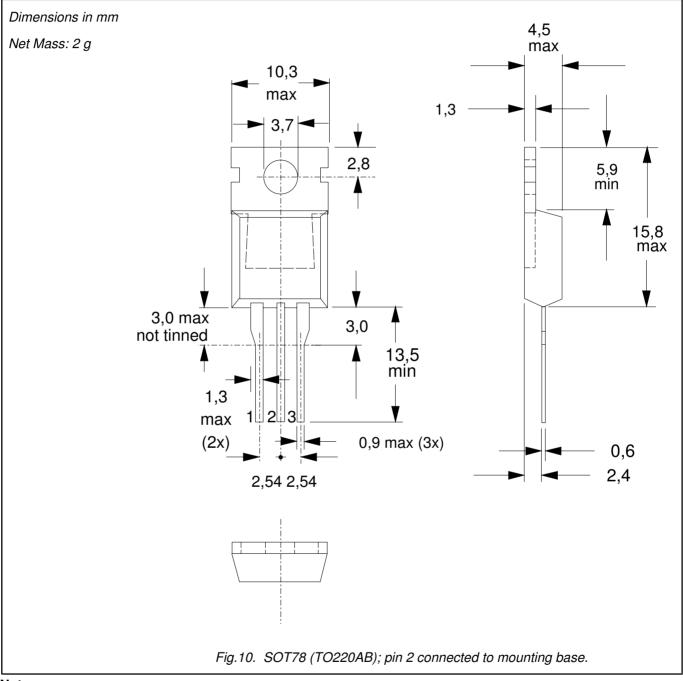
**BYV44** series

# Dual rectifier diodes ultrafast



Dual rectifier diodes ultrafast

### **MECHANICAL DATA**



**Notes** 1. Refer to mounting instructions for SOT78 (TO220) envelopes. 2. Epoxy meets UL94 V0 at 1/8".

**BYV44** series

## Legal information

### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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#### **Contact information**

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